

### General Description

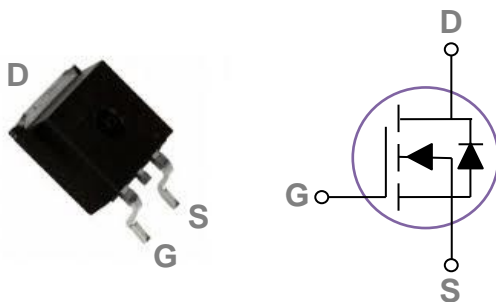
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
40V	1.5mΩ	220A

### Features

- 40V, 220A,  $R_{DS(ON)} = 1.5m\Omega @ V_{GS} = 10V$
- Improved  $dv/dt$  capability
- Fast switching
- Green Device Available

### TO263 Pin Configuration



### Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2<sup>nd</sup> SR

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	220	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	139	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	880	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	1377	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	166	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	208	W
	Power Dissipation – Derate above $25^\circ\text{C}$	1.66	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	0.6	$^\circ\text{C/W}$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}, I_D=1\text{mA}$	---	0.03	---	$V/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=40V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=32V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>3</sup>	$V_{GS}=10V, I_D=20A$	---	1	1.5	$m\Omega$
		$V_{GS}=6V, I_D=15A$	---	1.65	2.5	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.5	2.5	3.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.6	---	$mV/^\circ\text{C}$
gfs	Forward Transconductance	$V_{DS}=10V, I_D=2A$	---	16	---	S

**Dynamic Characteristics**

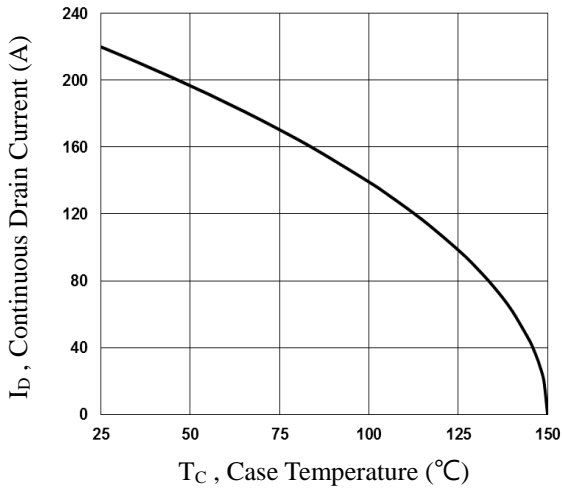
$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{DS}=32V, V_{GS}=10V, I_D=10A$	---	295	450	nC
$Q_{gs}$	Gate-Source Charge <sup>3,4</sup>		---	72.9	110	
$Q_{gd}$	Gate-Drain Charge <sup>3,4</sup>		---	121	180	
$T_{d(on)}$	Turn-On Delay Time <sup>3,4</sup>	$V_{DD}=32V, V_{GS}=10V, R_G=6\Omega$ $I_D=1A$	---	74	148	ns
$T_r$	Rise Time <sup>3,4</sup>		---	190	380	
$T_{d(off)}$	Turn-Off Delay Time <sup>3,4</sup>		---	450	900	
$T_f$	Fall Time <sup>3,4</sup>		---	400	800	
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, F=1\text{MHz}$	---	17760	26600	pF
$C_{oss}$	Output Capacitance		---	1990	3000	
$C_{rss}$	Reverse Transfer Capacitance		---	341	510	
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	---	2.07	3.1	$\Omega$

**Drain-Source Diode Characteristics**

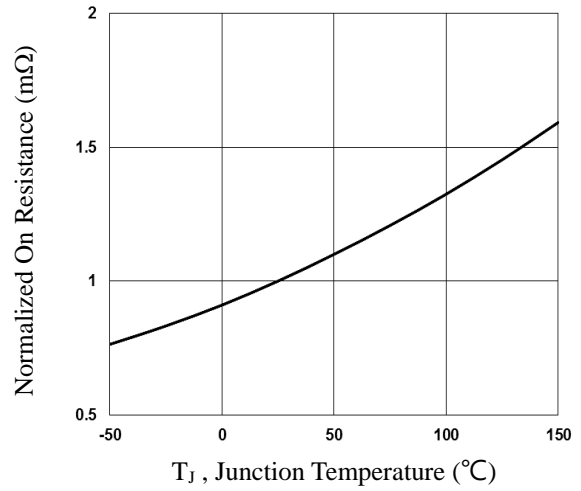
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V, \text{Force Current}$	---	---	220	A
$I_{SM}$	Pulsed Source Current <sup>3</sup>		---	---	440	A
$V_{SD}$	Diode Forward Voltage <sup>3</sup>	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V

Note :

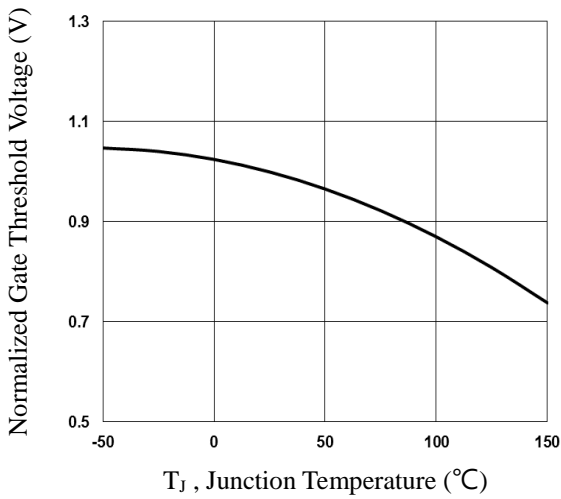
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=166A., \text{Starting } T_J=25^\circ\text{C}$
3. The data tested by pulsed , pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.



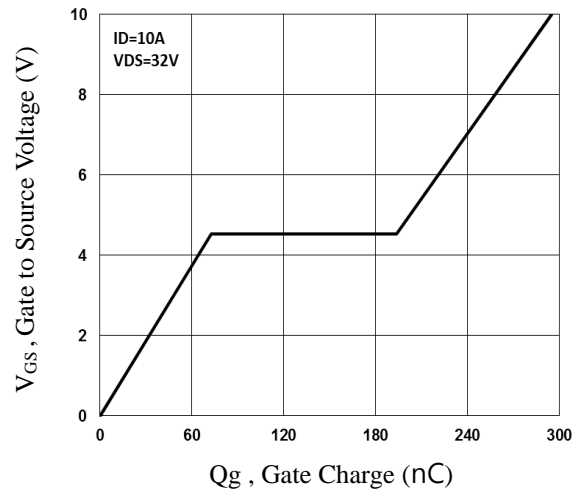
**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**



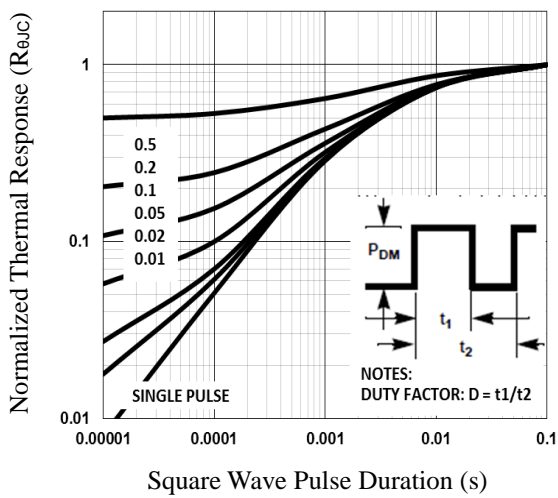
**Fig.2 Normalized R<sub>DS(on)</sub> vs. T<sub>j</sub>**



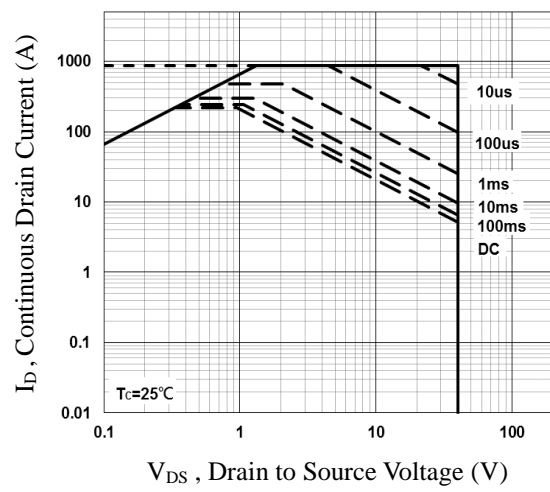
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**



**Fig.4 Gate Charge Waveform**



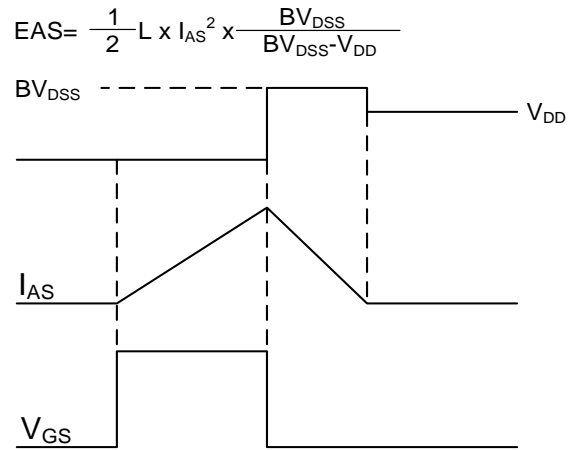
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**



**Fig.7 Switching Time Waveform**



**Fig.8 EAS Waveform**

TO263 PACKAGE INFORMATION

